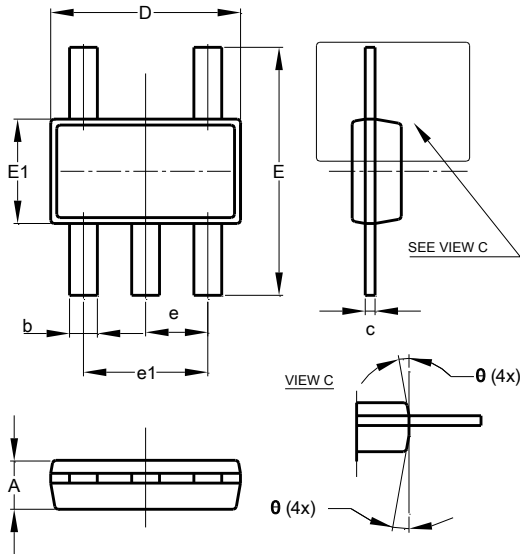


Package Outline Dimensions

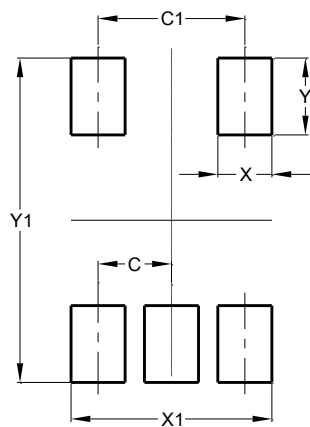
TSOT25F



TSOT25F			
Dim	Min	Max	Typ
A	0.700	0.775	0.750
b	0.350	0.500	-
c	0.100	0.200	-
D	2.800	3.100	2.900
E	3.700	3.900	3.800
E1	1.500	1.700	1.600
e	-	-	0.950
e1	-	-	1.900
θ	4°	12°	10°
All Dimensions in mm			

Suggested Pad Layout

TSOT25F



Dimensions	Value (in mm)
C	0.950
C1	1.900
X	0.700
X1	2.600
Y	1.000
Y1	4.220

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.